NOTE:
For Boost Follower Configuration:
- Populate R31, R45 and C3 and set R9 = 15.3k
- Change R1 to 0.33 Ohm

For Fixed Output Boost PFC configuration:
- Do not populate R21 and Q5 and set R9 = 6.49k

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Update the Label Text in the Label Table as needed for each Assembly Variant.

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Label Table

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Version control disabled

SVN Rev: TIDA-00701

Number: RevB

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